

Amendments to the Claims:

1-15. (Cancelled)

16. (Currently Amended) A probe card mountable to a tester for testing a device, wherein the tester includes a test head interphase board, said probe card comprising: a package having solder balls mountable to the test head interphase board, and having a single pad on which is disposed electrically conductive material configured to electrically contact a plurality of bumps on the device.

17. (Previously Presented) The probe card as recited in claim 16, wherein the probe card does not have any probe pins.

18. (Previously Presented) The probe card as recited in claim 16, wherein the probe card is configured to make electrical contact with bumps on the device without using probe pins.

19. (Currently Amended) A method for testing a device under test (DUT), said method comprising: providing a tester which includes a test head interphase board; providing a probe card which includes a package having solder balls mounted to the test head interphase board, and having a single pad on which is disposed electrically conductive surface material; providing a device under test (DUT)/load board which is configured to retain a substrate, said tester being connected to a Digital Sampling Oscilloscope (DSO); contacting said electrically conductive

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